

## Agilent HCPL-260L/ 060L/263L/063L High Speed LVTTL Compatible 3.3 Volt Optocouplers

**Data Sheet** 

## Description

The HCPL-260L/060L/263L/063L are optically coupled gates that combine a GaAsP light emitting diode and an integrated high gain photo detector. An enable input allows the detector to be strobed. The output of the detector IC is an open collector Schottky-clamped transistor. The internal shield provides a guaranteed common mode transient immunity specification of 5 kV/µs.

This unique design provides maximum AC and DC circuit isolation while achieving LVTTL/LVCMOS compatibility. The optocoupler AC and DC operational parameters are guaranteed from -40°C to +85°C allowing trouble-free system performance.

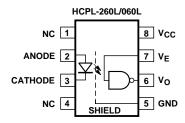
#### Features

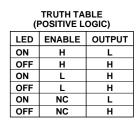
- Low power consumption
- 15 kV/µs minimum Common Mode Rejection (CMR) at V<sub>CM</sub> = 50 V
- High speed: 15 MBd typical
- LVTTL/LVCMOS compatible
- Low input current capability: 5 mA
- Guaranteed AC and DC performance over temperature: -40°C to +85°C
- Available in 8-pin DIP, SOIC-8
- Strobable output (single channel products only)
- Safety approvals; UL, CSA, VDE 0884

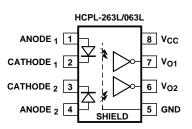
## Applications

- Isolated line receiver
- Computer-peripheral interfaces
- Microprocessor system interfaces
- Digital isolation for A/D, D/A conversion
- Switching power supply
- Instrument input/output isolation
- Ground loop elimination
- Pulse transformer replacement
- Field buses

## **Functional Diagram**









A 0.1  $\mu F$  bypass capacitor must be connected between pins 5 and 8.

CAUTION: It is advised that normal static precautions be taken in handling and assembly of this component to prevent damage and/or degradation which may be induced by ESD.



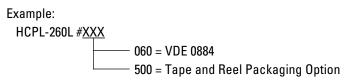
These optocouplers are suitable for high speed logic interfacing, input/output buffering, as line receivers in environments that conventional line receivers cannot tolerate and are recommended for use in extremely high ground or induced noise environments.

These optocouplers are available in an 8-pin DIP and industry standard SO-8 package. The part numbers are as follows:

8-pin DIP	SO-8 Package
HCPL-260L	HCPL-060L
HCPL-263L	HCPL-063L

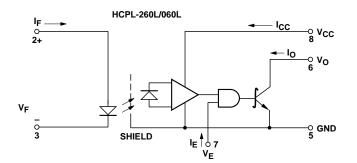
## **Ordering Information**

Specify Part Number followed by Option Number (if desired).

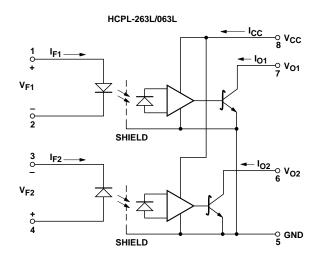


Option data sheets available. Contact Agilent sales representative or authorized distributor for information.

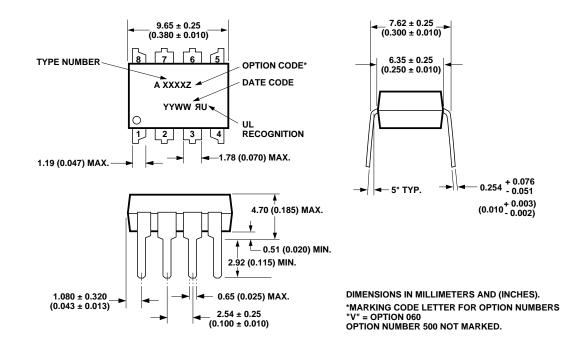
## Schematic



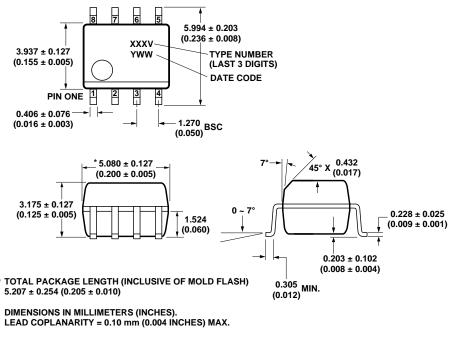
USE OF A 0.1  $\mu F$  BYPASS CAPACITOR CONNECTED BETWEEN PINS 5 AND 8 IS RECOMMENDED (SEE NOTE 5).



## Package Outline Drawings 8-Pin DIP Package

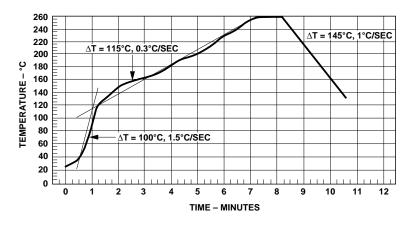


#### Small Outline SO-8 Package



OPTION NUMBER 500 NOT MARKED.

# Solder Reflow Temperature Profile (Surface Mount Option Parts)



NOTE: USE OF NON-CHLORINE ACTIVATED FLUXES IS HIGHLY RECOMMENDED.

## **Regulatory Information**

The HCPL-260L/060L/263L/063L have been approved by the following organizations:

#### UL

Approval under UL 1577, Component Recognition Program, File E55361.

#### CSA

Approval under CSA Component Acceptance Notice #5, File CA 88324.

#### VDE

Approval according to VDE 0884/06.92.

## **Insulation and Safety Related Specifications**

Parameter	Symbol	8-Pin DIP (300 Mil) Value	SO-8 Value	Units	Conditions
Minimum External Air Gap (External Clearance)	L (101)	7.1	4.9	mm	Measured from input terminals to output terminals, shortest distance through air.
Minimum External Tracking (External Creepage)	L (102)	7.4	4.8	mm	Measured from input terminals to output terminals, shortest distance path along body.
Minimum Internal Plastic Gap (Internal Clearance)		0.08	0.08	mm	Through insulation distance, conductor to conductor, usually the direct distance between the photoemitter and photodetector inside the optocoupler cavity.
Tracking Resistance (Comparative Tracking Index)	CTI	200	200	Volts	DIN IEC 112/VDE 0303 Part 1
Isolation Group		Illa	Illa		Material Group (DIN VDE 0110, 1/89, Table 1)

## **VDE 0884 Insulation Related Characteristics**

Description	Symbol	PDIP Option 060	SO-8 Option 60	Units
Installation classification per DIN VDE 0110/1.89, Table 1				
for rated mains voltage $\leq$ 150 V rms			I-IV	
for rated mains voltage $\leq$ 300 V rms		I-IV	1-111	
for rated mains voltage $\leq$ 600 V rms		1-111	1-11	
Climatic Classification		55/85/21	55/85/21	
Pollution Degree (DIN VDE 0110/1.89)		2	2	
Maximum Working Insulation Voltage	V <sub>IORM</sub>	630	566	V <sub>peak</sub>
Input to Output Test Voltage, Method b*				
V <sub>IORM</sub> x 1.875 = V <sub>PR</sub> , 100% Production Test	V <sub>PR</sub>	1181	1063	V <sub>peak</sub>
with t <sub>m</sub> = 1 sec, Partial Discharge < 5 pC				
Input to Output Test Voltage, Method a*				
V <sub>IORM</sub> x 1.5 = V <sub>PR</sub> , Type and Sample Test,	V <sub>PR</sub>	945	849	V <sub>peak</sub>
t <sub>m</sub> = 60 sec, Partial Discharge < 5 pC				
Highest Allowable Overvoltage*	VIOTM	6000	4000	V <sub>peak</sub>
(Transient Overvoltage, t <sub>ini</sub> = 10 sec)				•
Safety Limiting Values				
(Maximum values allowed in the event of a failure,				
also see Figure 16, Thermal Derating curve.)				
Case Temperature	Τs	175	150	°C
Input Current	I <sub>S,INPUT</sub>	230	150	mA
Output Power	P <sub>S,OUTPUT</sub>	600	600	mW
Insulation Resistance at T <sub>S</sub> , V <sub>IO</sub> = 500 V	R <sub>S</sub>	≥ 10 <sup>9</sup>	≥ 10 <sup>9</sup>	Ω

\*Refer to the front of the optocoupler section of the current catalog, under Product Safety Regulations section (VDE 0884), for a detailed description. Note: Isolation characteristics are guaranteed only within the safety maximum ratings which must be ensured by protective circuits in application.

## Absolute Maximum Ratings (No Derating Required up to 85°C)

Parameter	Symbol	Package**	Min.	Max.	Units	Note
Storage Temperature	Ts		-55	125	°C	
Operating Temperature†	T <sub>A</sub>		-40	85	°C	
Average Forward Input Current	IF	Single 8-Pin DIP Single SO-8		20	mA	2
		Dual 8-Pin DIP Dual SO-8		15		1, 3
Reverse Input Voltage	V <sub>R</sub>	8-Pin DIP, SO-8		5	V	1
Input Power Dissipation	PI			40	mW	
Supply Voltage (1 Minute Maximum)	V <sub>CC</sub>			7	V	
Enable Input Voltage (Not to Exceed V <sub>CC</sub> by more than 500 mV)	VE	Single 8-Pin DIP Single SO-8		V <sub>CC</sub> + 0.5	V	
Enable Input Current	IE			5	mA	
Output Collector Current	Io			50	mA	1
Output Collector Voltage	V <sub>0</sub>			7	V	1
Output Collector Power Dissipation	P <sub>0</sub>	Single 8-Pin DIP Single SO-8		85	mW	
		Dual 8-Pin DIP Dual SO-8		60		1, 4
Lead Solder Temperature (Through Hole Parts Only)	T <sub>LS</sub>	8-Pin DIP	260°C fo seating	r 10 sec., 1.6 n plane	nm below	
Solder Reflow Temperature Profile (Surface Mount Parts Only)		SO-8	See Pac section	kage Outline	Drawings	

\*\*Ratings apply to all devices except otherwise noted in the Package column.

## **Recommended Operating Conditions**

Parameter	Symbol	Min.	Max.	Units
Input Current, Low Level	I <sub>FL</sub> *	0	250	μA
Input Current, High Level <sup>[1]</sup>	I <sub>FH</sub> **	5	15	mA
Power Supply Voltage	V <sub>CC</sub>	2.7	3.3	V
Low Level Enable Voltage	V <sub>EL</sub>	0	0.8	V
High Level Enable Voltage	V <sub>EH</sub>	2.0	V <sub>CC</sub>	V
Operating Temperature	TA	-40	85	°C
Fan Out (at $R_L = 1 \ k\Omega$ ) <sup>[1]</sup>	Ν		5	TTL Loads
Output Pull-up Resistor	RL	330	4 k	Ω

\*The off condition can also be guaranteed by ensuring that V<sub>FL</sub>  $\leq$  0.8 volts. \*\*The initial switching threshold is 5 mA or less. It is recommended that 6.3 mA to 10 mA be used for best performance and to permit at least a 20% LED degradation guardband.

## **Electrical Specifications**

Over Recommended Temperature ( $T_A = -40^{\circ}C$ to +85°C) unless otherwise specified. All Typicals at V <sub>CC</sub> = 3.3 V,
$T_A = 25^{\circ}C$ . All enable test conditions apply to single channel products only. See Note 5.

Parameter	Sym.	Device	Min.	Тур.	Max.	Units	Test Conditions	Fig.	Note
High Level Output Current	I <sub>OH</sub> *			4.5	50	μA	$ \begin{array}{l} V_{CC} = 3.3 \ V, \ V_E = 2.0 \ V, \\ V_0 = 3.3 \ V, \ I_F = 250 \ \mu A \end{array} $	1	1, 15
Input Threshold Current	ITH			3.0	5.0	mA	$V_{CC} = 3.3 \text{ V}, \text{ V}_{E} = 2.0 \text{ V},$ $V_{0} = 0.6 \text{ V},$ $I_{0L}$ (Sinking) = 13 mA	2	15
Low Level Output Voltage	V <sub>0L</sub> *			0.35	0.6	V	$V_{CC} = 3.3 V, V_E = 2.0 V,$ I <sub>F</sub> = 5 mA, I <sub>OL</sub> (Sinking) = 13 mA	3	15
High Level Supply Current	ICCH	Single Dual		4.7 6.9	7.0 10.0	mA	$\begin{tabular}{ c c c c c } \hline V_E = 0.5 \ V & I_F = 0 \ mA \\ \hline V_{CC} = 3.3 \ V \\ \hline \end{tabular}$		
Low Level Supply Current	I <sub>CCL</sub>	Single Dual		7.0 8.7	10.0 15.0	mA	$\begin{tabular}{ c c c c c } \hline V_E = 0.5 \ V & I_F = 10 \ mA \\ \hline V_{CC} = 3.3 \ V \\ \hline \end{tabular}$		
High Level Enable Current	I <sub>EH</sub>			-0.5	-1.2	mA	$V_{CC} = 3.3 \text{ V}, \text{ V}_{E} = 2.0 \text{ V}$		
Low Level Enable Current	I <sub>EL</sub> *			-0.5	-1.2	mA	$V_{CC} = 3.3 \text{ V}, \text{ V}_{E} = 0.5 \text{ V}$		
High Level Enable Voltage	V <sub>EH</sub>		2.0			V			15
Low Level Enable Voltage	V <sub>EL</sub>				0.8	V			
Input Forward Voltage	V <sub>F</sub>		1.4	1.5	1.75*	V	T <sub>A</sub> = 25°C, I <sub>F</sub> = 10 mA	5	1
Input Reverse Breakdown Voltage	BV <sub>R</sub> *		5			V	I <sub>R</sub> = 10 μA		1
Input Diode Temperature Coefficient	$\Delta V_{F} / \Delta T_{A}$			-1.6		mV°C	I <sub>F</sub> = 10 mA		1
Input Capacitance	C <sub>IN</sub>			60		pF	f = 1 MHz, V <sub>F</sub> = 0 V		1

\*The JEDEC Registration specifies 0°C to +70°C. Agilent specifies -40°C to +85°C.

## **Switching Specifications**

Over Recommended Temperature (T<sub>A</sub> =  $-40^{\circ}$ C to  $+85^{\circ}$ C), V<sub>CC</sub> = 3.3 V, I<sub>F</sub> = 7.5 mA unless otherwise specified. All Typicals at  $T_A = 25^{\circ}C$ ,  $V_{CC} = 3.3 V$ .

Parameter	Sym.	Package**	Min.	Typ.	Max.	Units	Test Conditions	Fig.	Note
Propagation Delay Time to High Output Level	t <sub>PLH</sub>				90	ns	$\begin{array}{l} R_L = 350 \ \Omega \\ C_L = 15 \ pF \end{array}$	6, 7, 8	1, 6, 15
Propagation Delay Time to Low Output Level	t <sub>PHL</sub>				75	ns			1, 7, 15
Pulse Width Distortion	lt <sub>PHL</sub> – t <sub>PLH</sub> l	8-Pin DIP SO-8			25	ns	-	8	9, 15
Propagation Delay Skew	t <sub>PSK</sub>				40	ns	-		8, 9, 15
Output Rise Time (10-90%)	t <sub>r</sub>			45		ns			1, 15
Output Fall Time (90-10%)	t <sub>f</sub>			20		ns	-		1, 15
Propagation Delay Time of Enable from V <sub>EH</sub> tp V <sub>EL</sub>	t <sub>ELH</sub>			45		ns	$ \begin{array}{l} {\sf R}_{\sf L} = 350 \ \Omega, \\ {\sf C}_{\sf L} = 15 \ {\sf pF}, \\ {\sf V}_{\sf EL} = 0 \ {\sf V}, \ {\sf V}_{\sf EH} = 3 \ {\sf V} \end{array} $	9	10
Propagation Delay Time of Enable from V <sub>EL</sub> to V <sub>EH</sub>	t <sub>EHL</sub>			30		ns			11

\*JEDEC registered data for the 6N137. \*\*Ratings apply to all devices except otherwise noted in the Package column.

Parameter	Sym.	Device	Min.	Тур.	Units	<b>Test Conditions</b>		Fig.	Note
Logic High	ICMHI	HCPL-263L	15,000	25,000	V/µs	V <sub>CM</sub>   = 10 V	$V_{CC} = 3.3 \text{ V}, \text{ I}_{\text{F}} = 0 \text{ mA},$	11	12, 14, 15
Common		HCPL-063L					$V_{0(MIN)} = 2 V,$		
Mode							$R_{L} = 350 \Omega$ , $T_{A} = 25$ °C		
Transient		HCPL-260L	15,000	25,000		V <sub>CM</sub>   = 50 V			
Immunity		HCPL-060L							
Logic Low	ICML	HCPL-263L	15,000	25,000	V/µs	V <sub>CM</sub>   = 10 V	$V_{CC} = 3.3 \text{ V}, \text{ I}_{\text{F}} = 7.5 \text{ mA},$	11	13, 14, 15
Common		HCPL-063L					$V_{0(MAX)} = 0.8 V,$		
Mode							$R_{L} = 350 \Omega$ , $T_{A} = 25$ °C		
Transient		HCPL-260L	15,000	25,000		V <sub>CM</sub>   = 50 V			
Immunity		HCPL-060L							

## **Package Characteristics**

All Typicals at  $T_A = 25^{\circ}C$ .

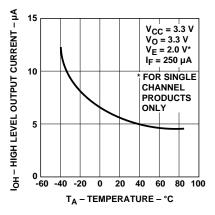
Parameter	Sym.	Package	Min.	Тур.	Max	Units	Test Conditions	Fig.	Note
Input-Output Insulation	I <sub>I-0</sub> *	Single 8-Pin DIP Single SO-8			1	μA	$\begin{array}{l} 45\% \text{ RH, t} = 5 \text{ s,} \\ V_{1-0} = 3 \text{ kV DC, T}_{A} = 25^{\circ}\text{C} \end{array}$		16, 17
Input-Output Momentary Withstand Voltage**	V <sub>ISO</sub>	8-Pin DIP, SO-8	2500			V rms	$\begin{array}{l} RH\leq 50\%,t=1min,\\ T_{A}=25^{\circ}C \end{array}$	16, 17	
Input-Output Resistance	R <sub>I-0</sub>	8-Pin, SO-8		10 <sup>12</sup>		Ω	V <sub>I-0</sub> =500 V dc		1, 16, 19
Input-Output Capacitance	C <sub>I-0</sub>	8-Pin DIP, SO-8		0.6		pF	f = 1 MHz, T <sub>A</sub> = 25°C		1, 16, 19
Input-Input Insulation Leakage Current	I <sub>I-1</sub>	Dual Channel		0.005		μΑ	$\label{eq:RH} \begin{array}{l} RH \leq 45\%,  t=5  s, \\ V_{I-I} = 500   V \end{array}$		20
Resistance (Input-Input)	R <sub>I-I</sub>	Dual Channel		10 <sup>11</sup>		Ω			20
Capacitance (Input-Input)	CI-I	Dual 8-Pin Dip		0.03		pG	f = 1 MHz		20
		Dual SO-8		0.25					

\*The JEDEC Registration specifies 0°C to +70°C. Agilent specifies -40°C to +85°C.

\*\*The Input-Output Momentary Withstand Voltage is a dielectric voltage rating that should not be interpreted as an input-output continuous voltage rating. For the continuous voltage rating refer to the VDE 0884 Insulation Characteristics Table (if applicable), your equipment level safety specification or Agilent Application Note 1074 entitled "Optocoupler Input-Output Endurance Voltage."

#### Notes:

- 1. Each channel.
- 2. Peaking circuits may produce transient input currents up to 50 mA, 50 ns maximum pulse width, provided average current does not exceed 20 mA.
- 3. Peaking circuits may produce transient input currents up to 50 mA, 50 ns maximum pulse width, provided average current does not exceed 15 mA.
- 4. Derate linearly above +80°C free-air temperature at a rate of 2.7 mW/°C for the SOIC-8 package.
- 5. Bypassing of the power supply line is required, with a 0.1 μF ceramic disc capacitor adjacent to each optocoupler as illustrated in Figure 11. Total lead length between both ends of the capacitor and the isolator pins should not exceed 20 mm.
- 6. The t<sub>PLH</sub> propagation delay is measured from the 3.75 mÅ point on the falling edge of the input pulse to the 1.5 V point on the rising edge of the output pulse.
- 7. The t<sub>PHL</sub> propagation delay is measured from the 3.75 mA point on the rising edge of the input pulse to the 1.5 V point on the falling edge of the output pulse.
- 8. t<sub>PSK</sub> is equal to the worst case difference in t<sub>PHL</sub> and/or t<sub>PLH</sub> that will be seen between units at any given temperature and specified test conditions.
- 9. See test circuit for measurement details.
- 10. The t<sub>ELH</sub> enable propagation delay is measured from the 1.5 V point on the falling edge of the enable input pulse to the 1.5 V point on the rising edge of the output pulse.
- 11. The t<sub>ELH</sub> enable propagation delay is measured from the 1.5 V point on the rising edge of the enable input pulse to the 1.5 V point on the falling edge of the output pulse.
- 12. CM<sub>H</sub> is the maximum tolerable rate of rise on the common mode voltage to assure that the output will remain in a high logic state (i.e., V<sub>0</sub> > 2.0 V).
- 13.  $CM_L$  is the maximum tolerable rate of fall of the common mode voltage to assure that the output will remain in a low logic state (i.e.,  $V_o < 0.8$  V).
- 14. For sinusoidal voltages,  $(IdV_{CM} | / dt)_{max} = \pi f_{CM} V_{CM} (p-p)$ .
- 15. No external pull up is required for a high logic state on the enable input. If the V<sub>E</sub> pin is not used, tying V<sub>E</sub> to V<sub>CC</sub> will result in improved CMR performance. For single channel products only. See application information provided.
- 16. Device considered a two-terminal device: pins 1, 2, 3, and 4 shorted together, and pins 5, 6, 7, and 8 shorted together.
- 17. In accordance with UL 1577, each optocoupler is proof tested by applying an insulation test voltage ≥ 3000 V rms for one second (leakage detection current limit, I<sub>1-0</sub> ≤ 5 μA). This test is performed before the 100% production test for partial discharge (Method b) shown in the VDE 0884 Insulation Characteristics Table, if applicable.
- 18. In accordance with UL 1577, each optocoupler is proof tested by applying an insulation test voltage ≥ 6000 V rms for one second (leakage detection current limit, I<sub>1-0</sub> ≤ 5 µA). This test is performed before the 100% production test for partial discharge (Method b) shown in the VDE 0884 Insulation Characteristics Table, if applicable.
- 19. Measured between the LED anode and cathode shorted together and pins 5 through 8 shorted together. For dual channel products only.
- 20. Measured between pins 1 and 2 shorted together, and pins 3 and 4 shorted together. For dual channel products only.



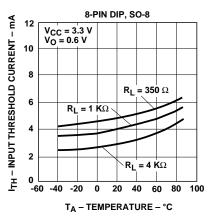
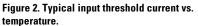


Figure 1. Typical high level output current vs. temperature.



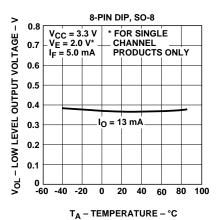
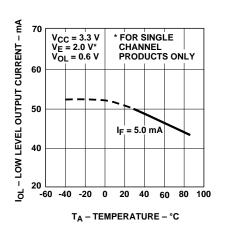


Figure 3. Typical low level output voltage vs. temperature.



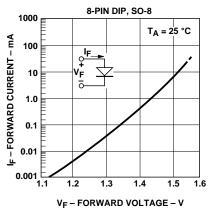
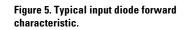


Figure 4. Typical low level output current vs. temperature.



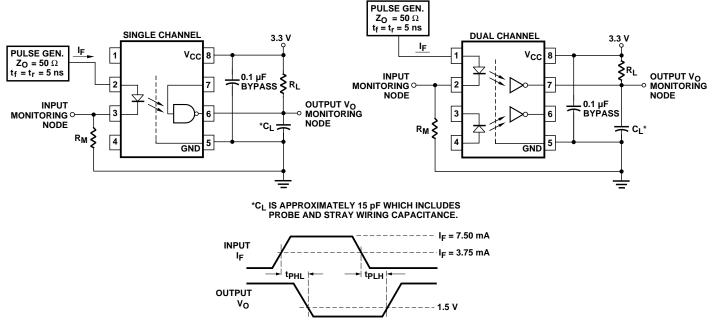
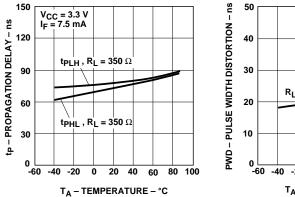


Figure 6. Test circuit for  $t_{PHL}$  and  $t_{PLH}$ .



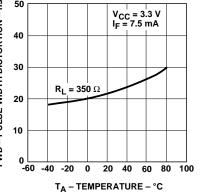


Figure 7. Typical propagation delay vs. temperature.

Figure 8. Typical pulse width distortion vs. temperature.

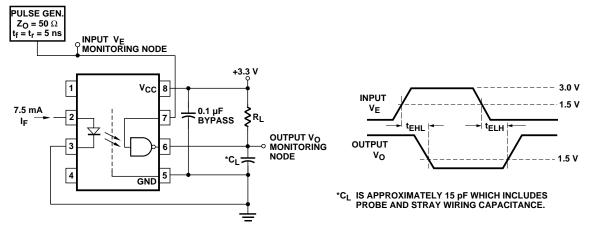


Figure 9. Test circuit for t<sub>EHL</sub> and t<sub>ELH</sub>.

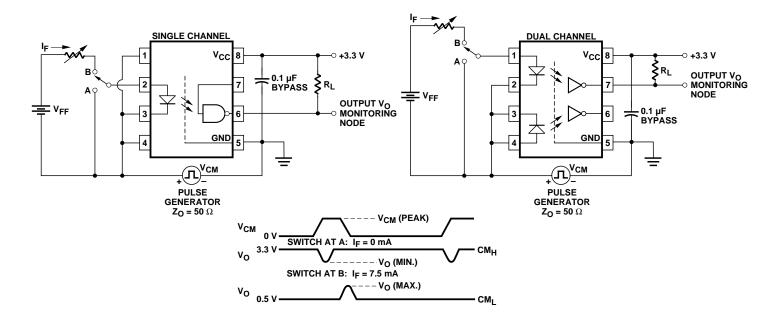


Figure 10. Test circuit for common mode transient immunity and typical waveforms.

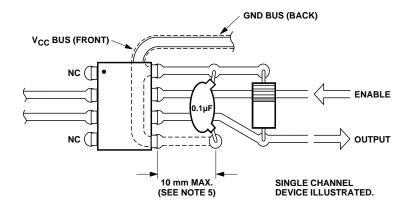
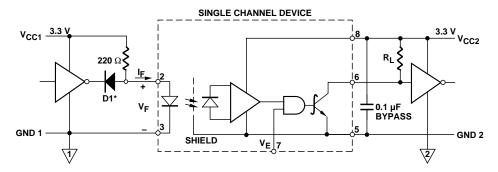


Figure 11. Recommended printed circuit board layout.



\*DIODE D1 (1N916 OR EQUIVALENT) IS NOT REQUIRED FOR UNITS WITH OPEN COLLECTOR OUTPUT.

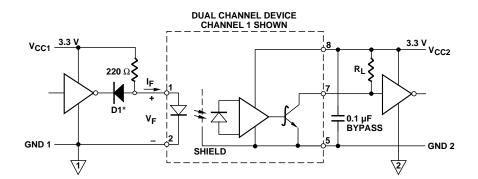


Figure 12. Recommended LVTTL interface circuit.

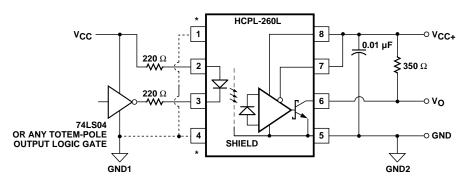
## Application Information Common-Mode Rejection for HCPL-260L Families:

Figure 13 shows the recommended drive circuit for optimal common-mode rejection performance. Two main points to note are:

- 1. The enable pin is tied to  $V_{CC}$  rather than floating (this applies to single-channel parts only).
- 2. Two LED-current setting resistors are used instead of one. This is to balance  $I_{LED}$  variation during commonmode transients.

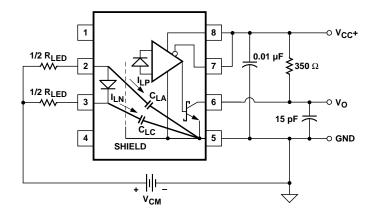
If the enable pin is left floating, it is possible for common-mode transients to couple to the enable pin, resulting in common-mode failure. This failure mechanism only occurs when the LED is on and the output is in the Low State. It is identified as occurring when the transient output voltage rises above 0.8 V. Therefore, the enable pin should be connected to either  $V_{\mbox{\scriptsize CC}}$  or logic-level high for best common-mode performance with the output low (CMR<sub>L</sub>). This failure mechanism is only present in single-channel parts which have the enable function.

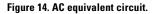
Also, common-mode transients can capacitively couple from the LED anode (or cathode) to the output-side ground causing current to be shunted away from the LED (which can be bad if the LED is on) or conversely cause current to be injected into the LED (bad if the LED is meant to be off). Figure 14 shows the parasitic capacitances which exists between LED anode/cathode and output ground  $(C_{LA} \text{ and } C_{LC})$ . Also shown in Figure 14 on the input side is an AC-equivalent circuit.



\* HIGHER CMR MAY BE OBTAINABLE BY CONNECTING PINS 1, 4 TO INPUT GROUND (GND1).

Figure 13. Recommended drive circuit for High-CMR.





For transients occurring when the LED is on, common-mode rejection (CMR<sub>L</sub>, since the output is in the "low" state) depends upon the amount of LED current drive (I<sub>F</sub>). For conditions where I<sub>F</sub> is close to the switching threshold (I<sub>TH</sub>), CMR<sub>L</sub> also depends on the extent which I<sub>LP</sub> and I<sub>LN</sub> balance each other. In other words, any condition where common-mode transients cause a momentary decrease in I<sub>F</sub> will cause common-mode failure for transients which are fast enough.

Likewise for common-mode transients which occur when the LED is off (i.e.  $\text{CMR}_{\text{H}}$ , since the

output is "high"), if an imbalance between  $I_{LP}$  and  $I_{LN}$  results in a transient  $I_F$  equal to or greater than the switching threshold of the optocoupler, the transient "signal" may cause the output to spike below 2 V (which constitutes a CMR<sub>H</sub> failure).

By using the recommended circuit in Figure 13, good CMR can be achieved. The balanced  $I_{LED}$ -setting resistors help equalize  $I_{LP}$  and  $I_{LN}$  to reduce the amount by which  $I_{LED}$  is modulated from transient coupling through  $C_{LA}$  and  $C_{LC}$ .

## CMR with Other Drive Circuits

CMR performance with drive circuits other than that shown in Figure 13 may be enhanced by following these guidelines:

- 1. Use of drive circuits where current is shunted from the LED in the LED "off" state (as shown in Figures 15 and 16). This is beneficial for good  $\rm CMR_{\rm H}$ .
- 2. Use of  $I_{FH} > 3.5$  mA. This is good for high CMR<sub>L</sub>.

Figure 15 shows a circuit which can be used with any totem-poleoutput TTL/LSTTL/HCMOS logic gate. The buffer PNP transistor allows the circuit to be used with logic devices which have low current-sinking capability. It also helps maintain the driving-gate power-supply current at a constant level to minimize ground shifting for other devices connected to the input-supply ground.

When using an open-collector TTL or open-drain CMOS logic gate, the circuit in Figure 16 may be used. When using a CMOS gate to drive the optocoupler, the circuit shown in Figure 17 may be used. The diode in parallel with the  $R_{LED}$  speeds the turn-off of the optocoupler LED.

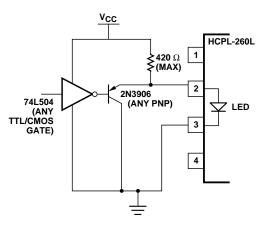
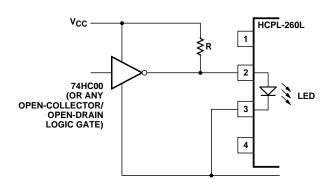


Figure 15. TTL interface circuit.





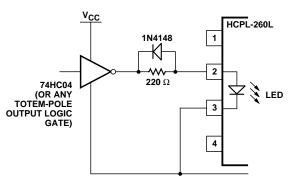


Figure 17. CMOS gate drive circuit.

#### www.agilent.com/semiconductors

For product information and a complete list of distributors, please go to our web site. For technical assistance call:

Americas/Canada: +1 (800) 235-0312 or

(408) 654-8675 Europe: +49 (0) 6441 92460

China: 10800 650 0017

Hong Kong: (+65) 6271 2451

India, Australia, New Zealand: (+65) 6271 2394

Japan: (+81 3) 3335-8152(Domestic/International), or 0120-61-1280(Domestic Only)

Korea: (+65) 6271 2194

Malaysia, Singapore: (+65) 6271 2054 Taiwan: (+65) 6271 2654

Data subject to change. Copyright © 2002 Agilent Technologies, Inc. Obsoletes 5988-8061EN October 15, 2002 5988-8186EN



🔆 Agilent Technologies